- 'LS377 and 'LS378 Contain Eight and Six Flip-Flops, Respectively, with Single-Rail Outputs

- 'LS379 Contains Four Flip-Flops with Double-Rail Outputs

- Individual Data Input to Each Flip-Flop

- Applications Include:
  Buffer/Storage Registers
  Shift Registers
  Pattern Generators

description

These monolithic, positive-edge-triggered flip-flops utilize TTL circuitry to implement D-type flip-flop logic with an enable input. The 'LS377, 'LS378, and 'LS379 devices are similar to 'LS273, 'LS174, and 'LS175, respectively, but feature a common enable instead of a common clear.
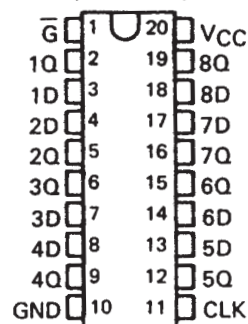
Information at the D inputs meeting the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock pulse if the enable input $\overline{G}$ is low. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When the clock input is at either the high or low level, the D input signal has no effect at the output. The circuits are designed to prevent false clocking by transitions at the $\overline{G}$ input.

These flip-flops are guaranteed to respond to clock frequencies ranging from 0 to 30 MHz while maximum clock frequency is typically 40 megahertz. Typical power dissipation is 10 milliwatts per flip-flop.
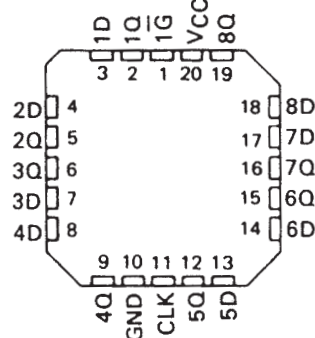
SN54LS377 . . . J PACKAGE
SN74LS377 . . . DW OR N PACKAGE
(TOP VIEW)

Pin		Pin
$\overline{G}$	1	20	V_{CC}
1Q	2	19	8Q
1D	3	18	8D
2D	4	17	7D
2Q	5	16	7Q
3Q	6	15	6Q
3D	7	14	6D
4D	8	13	5D
4Q	9	12	5Q
GND	10	11	CLK

SN54LS377 . . . FK PACKAGE
(TOP VIEW)

Top pins: 1D (3), 1Q (2), 1G (1), V_CC (20), 8Q (19)

Left			Right
2D	4	18	8D
2Q	5	17	7D
3Q	6	16	7Q
3D	7	15	6Q
4D	8	14	6D

Bottom pins: 4Q (9), GND (10), CLK (11), 5Q (12), 5D (13)

SN54LS378 . . . J OR W PACKAGE
SN74LS378 . . . D OR N PACKAGE
(TOP VIEW)

Pin		Pin
$\overline{G}$	1	16	V_{CC}
1Q	2	15	6Q
1D	3	14	6D
2D	4	13	5D
2Q	5	12	5Q
3D	6	11	4D
3Q	7	10	4Q
GND	8	9	CLK
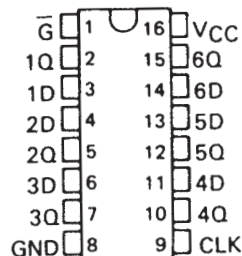
SN54LS378 . . . FK PACKAGE
(TOP VIEW)
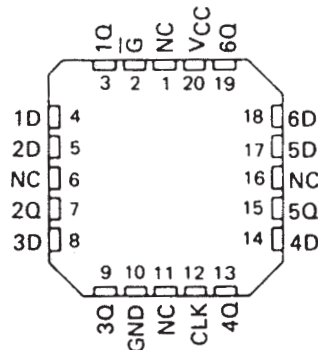
Top pins: 1Q (3), 1G (2), NC (1), V_CC (20), 6Q (19)

Left			Right
1D	4	18	6D
2D	5	17	5D
NC	6	16	NC
2Q	7	15	5Q
3D	8	14	4D

Bottom pins: 3Q (9), GND (10), NC (11), CLK (12), 4Q (13)

NC – No internal connection

FUNCTION TABLE
(EACH FLIP-FLOP)

INPUTS			OUTPUTS	
$\overline{G}$	CLOCK	DATA	Q	$\overline{Q}$
H	X	X	Q_0	$\overline{Q}_0$
L	↑	H	H	L
L	↑	L	L	H
X	L	X	Q_0	$\overline{Q}_0$

TEXAS INSTRUMENTS

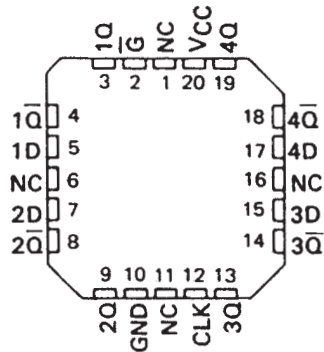# SN54LS377, SN54LS378, SN54LS379,
SN74LS377, SN74LS378, SN74LS379
OCTAL, HEX, AND QUAD D-TYPE FLIP-FLOPS WITH ENABLE

SN54LS379 . . . J OR W PACKAGE
SN74LS379 . . . D OR N PACKAGE
(TOP VIEW)

$\overline{G}$	1	16	V$_{CC}$
1Q	2	15	4Q
1$\overline{Q}$	3	14	4$\overline{Q}$
1D	4	13	4D
2D	5	12	3D
2$\overline{Q}$	6	11	3$\overline{Q}$
2Q	7	10	3Q
GND	8	9	CLK

SN54LS379 . . . FK PACKAGE
(TOP VIEW)

Top pins (3,2,1,20,19): 1Q, $\overline{G}$, NC, V$_{CC}$, 4Q

1$\overline{Q}$	4	18	4Q
1D	5	17	4D
NC	6	16	NC
2D	7	15	3D
2$\overline{Q}$	8	14	3$\overline{Q}$

Bottom pins (9,10,11,12,13): 2Q, GND, NC, CLK, 3Q

NC – No internal connection

logic diagram (positive logic)

CLOCK

CK
EN

D

CK

D

$\overline{Q}$ Q

TO   7 ('LS377)
      5 ('LS378)
      3 ('LS379)
OTHER FLIP-FLOPS

ENABLE
$\overline{G}$

$\overline{Q}$ Q

$\overline{Q}$
('LS379
ONLY)

logic symbols[†]

'LS377

$\overline{G}$ (1)	G1	
CLK (11)	1C2	
1D (3)	2D	(2) 1Q
2D (4)		(5) 2Q
3D (7)		(6) 3Q
4D (8)		(9) 4Q
5D (13)		(12) 5Q
6D (14)		(15) 6Q
7D (17)		(16) 7Q
8D (18)		(19) 8Q

'LS378

$\overline{G}$ (1)	G1	
CLK (9)	1C2	
1D (3)	2D	(2) 1Q
2D (4)		(5) 2Q
3D (6)		(7) 3Q
4D (11)		(10) 4Q
5D (13)		(12) 5Q
6D (14)		(15) 6Q

'LS379

$\overline{G}$ (1)	G1	
CLK (9)	1C2	
1D (4)	2D	(2) 1Q
		(3) 1$\overline{Q}$
2D (5)		(7) 2Q
		(6) 2$\overline{Q}$
3D (12)		(10) 3Q
		(11) 3$\overline{Q}$
4D (13)		(15) 4Q
		(14) 4$\overline{Q}$

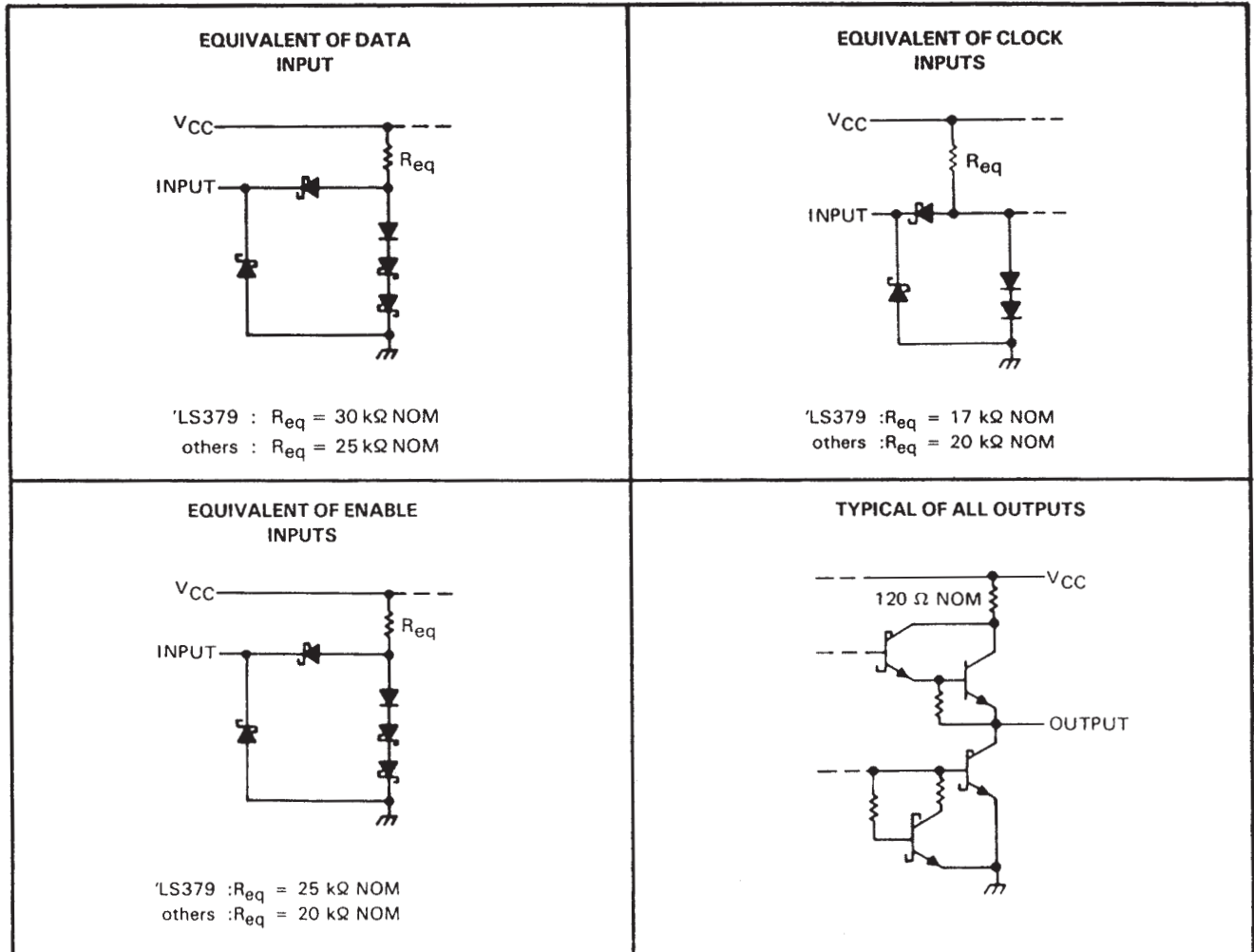[†] These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for DW, J, and N packages.

schematics of inputs and outputs

EQUIVALENT OF DATA INPUT

V_{CC}
R_{eq}
INPUT

'LS379 : R_{eq} = 30 kΩ NOM
others : R_{eq} = 25 kΩ NOM

EQUIVALENT OF CLOCK INPUTS

V_{CC}
R_{eq}
INPUT

'LS379 : R_{eq} = 17 kΩ NOM
others : R_{eq} = 20 kΩ NOM

EQUIVALENT OF ENABLE INPUTS

V_{CC}
R_{eq}
INPUT

'LS379 : R_{eq} = 25 kΩ NOM
others : R_{eq} = 20 kΩ NOM

TYPICAL OF ALL OUTPUTS

120 Ω NOM
V_{CC}
OUTPUT

absolute maximum rating over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . 7 V
Input voltage . . . . 7 V
Operating free-air temperature range: SN54LS' . . . . –55°C to 125°C
                                        SN74LS' . . . . 0°C to 70°C
Storage temperature range . . . . –65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN54LS' MIN	SN54LS' NOM	SN54LS' MAX	SN74LS' MIN	SN74LS' NOM	SN74LS' MAX	UNIT
Supply voltage, V_{CC}		4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}				−400			−400	µA
Low-level output current, I_{OL}				4			8	mA
Clock frequency, f_{clock}		0		30	0		30	MHz
Width of clock pulse, t_w		20			20			ns
Setup time, t_{su}	Data input	20†			20†			ns
	Enable active-state	25†			25†			
	Enable inactive-state	10†			10†			
Hold time, t_h	Data and enable	5†			5†			ns
Operating free-air temperature, T_A		−55		125	0		70	°C

†The arrow indicates that the rising edge of the clock pulse is used for reference.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		SN54LS' MIN	SN54LS' TYP‡	SN54LS' MAX	SN74LS' MIN	SN74LS' TYP‡	SN74LS' MAX	UNIT
V_{IH}	High-level input voltage			2			2			V
V_{IL}	Low-level input voltage					0.7			0.8	V
V_{IK}	Input clamp voltage	V_{CC} = MIN,	I_I = −18 mA			−1.5			−1.5	V
V_{OH}	High-level output voltage	V_{CC} = MIN, V_{IH} = 2 V, $V_{IL} = V_{IL}$ max, I_{OH} = −400 µA		2.5	3.5		2.7	3.5		V
V_{OL}	Low-level output voltage	V_{CC} = MIN, V_{IH} = 2 V, $V_{IL} = V_{IL}$ max	I_{OL} = 4 mA		0.25	0.4		0.25	0.4	V
			I_{OL} = 8 mA					0.35	0.5	
I_I	Input current at maximum input voltage	V_{CC} = MAX,	V_I = 7 V			0.1			0.1	mA
I_{IH}	High-level input current	V_{CC} = MAX,	V_I = 2.7 V			20			20	µA
I_{IL}	Low-level input current	V_{CC} = MAX,	V_I = 0.4 V			−0.4			−0.4	mA
I_{OS}	Short-circuit output current§	V_{CC} = MAX		−20		−100	−20		−100	mA
I_{CC}	Supply current	V_{CC} = MAX, See Note 2	'LS377		17	28		17	28	mA
			'LS378		13	22		13	22	mA
			'LS379		9	15		9	15	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ Note more than one input should be shorted at a time, and duration of the short-circuit should not exceed one second.
NOTE 2: With all outputs open and ground applied to all data and enable inputs, I_{CC} is measured after a momentary ground, then 4.5 V, is applied to clock.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{max}	Maximum clock frequency	C_L = 15 pF, R_L = 2 kΩ See Note 3	30	40		MHz
t_{PLH}	Propagation delay time, low-to-high-level output from clock			17	27	ns
t_{PHL}	Propagation delay time, high-to-low-level output from clock			18	27	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

TEXAS
INSTRUMENTS
POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-8992501EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8992501EA SNJ54LS378J	Samples
JM38510/32504BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32504BRA	Samples
JM38510/32504BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32504BRA	Samples
JM38510/32504BSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32504BSA	Samples
JM38510/32504BSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32504BSA	Samples
M38510/32504BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32504BRA	Samples
M38510/32504BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32504BRA	Samples
M38510/32504BSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32504BSA	Samples
M38510/32504BSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32504BSA	Samples
SN54LS377J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS377J	Samples
SN54LS377J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS377J	Samples
SN54LS378J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS378J	Samples
SN54LS378J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS378J	Samples
SN54LS379J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS379J	Samples
SN54LS379J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS379J	Samples
SN74LS377DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS377	Samples
SN74LS377DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS377	Samples
SN74LS377DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS377	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS377DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS377	Samples
SN74LS377DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS377	Samples
SN74LS377DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS377	Samples
SN74LS377N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS377N	Samples
SN74LS377N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS377N	Samples
SN74LS377NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS377N	Samples
SN74LS377NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS377N	Samples
SN74LS377NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS377	Samples
SN74LS377NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS377	Samples
SN74LS378D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS378	Samples
SN74LS378D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS378	Samples
SN74LS378DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS378	Samples
SN74LS378DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS378	Samples
SN74LS378N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS378N	Samples
SN74LS378N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS378N	Samples
SNJ54LS377J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS377J	Samples
SNJ54LS377J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS377J	Samples
SNJ54LS377W	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS377W	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54LS377W	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS377W	Samples
SNJ54LS378J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8992501EA SNJ54LS378J	Samples
SNJ54LS378J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8992501EA SNJ54LS378J	Samples
SNJ54LS379FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 379FK	Samples
SNJ54LS379FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 379FK	Samples
SNJ54LS379J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS379J	Samples
SNJ54LS379J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS379J	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54LS377, SN54LS378, SN74LS377, SN74LS378 :

● Catalog: SN74LS377, SN74LS378

● Military: SN54LS377, SN54LS378

NOTE: Qualified Version Definitions:

　　　● Catalog - TI's standard catalog product

　　　● Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

Pocket Quadrants

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS377DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74LS377NSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74LS378DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS377DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74LS377NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74LS378DR	SOIC	D	16	2500	333.2	345.9	28.6

W (R−GDFP−F20)   CERAMIC DUAL FLATPACK

Base and Seating Plane

0.300 (7,62)
0.245 (6,22)

0.045 (1,14)
0.026 (0,66)

0.009 (0,23)
0.004 (0,10)

0.100 (2,45)
0.045 (1,14)

0.320 (8,13) MAX

1   20

0.022 (0,56)
0.015 (0,38)

0.050 (1,27)

0.540 (13,72) MAX

0.005 (0,13) MIN
4 Places

10   11

0.370 (9,40)   0.370 (9,40)
0.250 (6,35)   0.250 (6,35)

4040180−4/F 04/14

NOTES: A. All linear dimensions are in inches (millimeters).
         B. This drawing is subject to change without notice.
         C. This package can be hermetically sealed with a ceramic lid using glass frit.
         D. Index point is provided on cap for terminal identification only.
         E. Falls within Mil−Std 1835 GDFP2−F20

FK (S−CQCC−N**)   LEADLESS CERAMIC CHIP CARRIER
28 TERMINAL SHOWN

NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)

$\dfrac{0.020\ (0,51)}{0.010\ (0,25)}$

$\dfrac{0.020\ (0,51)}{0.010\ (0,25)}$

$\dfrac{0.080\ (2,03)}{0.064\ (1,63)}$

$\dfrac{0.055\ (1,40)}{0.045\ (1,14)}$

$\dfrac{0.045\ (1,14)}{0.035\ (0,89)}$

$\dfrac{0.028\ (0,71)}{0.022\ (0,54)}$

0.050 (1,27)

$\dfrac{0.045\ (1,14)}{0.035\ (0,89)}$

4040140/D 01/11

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
         C.   This package can be hermetically sealed with a metal lid.
         D.   Falls within JEDEC MS−004

TEXAS INSTRUMENTS
www.ti.com

D (R−PDSO−G16)   PLASTIC SMALL OUTLINE

0.394 (10,00)
0.386 (9,80)
⚠C

16   9

0.244 (6,20)
0.228 (5,80)

0.157 (4,00)
0.150 (3,80)   ⚠D

1   8

Pin 1
Index Area

0.050 (1,27)

0.020 (0,51)
0.012 (0,31)

⊕ | 0.010 (0,25) Ⓜ

0.069 (1,75) Max

0.010 (0,25)
0.004 (0,10)

0.010 (0,25)
0.005 (0,13)

▱ | 0.004 (0,10)

Gauge Plane

Seating Plane

0.010 (0,25)   0°−8°

0.050 (1,27)
0.016 (0,40)

4040047−6/M   06/11

NOTES: A. All linear dimensions are in inches (millimeters).
        B. This drawing is subject to change without notice.
     ⚠C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall
            not exceed 0.006 (0,15) each side.
     ⚠D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
        E. Reference JEDEC MS−012 variation AC.

Texas
INSTRUMENTS
www.ti.com

D (R−PDSO−G16)   PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)

Stencil Openings
(Note D)

←—14x1,27

16x0,55

←—14x1,27

16x1,50

5,40

5.40

Example
Non Soldermask Defined Pad

Example
Pad Geometry
(See Note C)

—0,60

1,55

Example
Solder Mask Opening
(See Note E)

—0,07

All Around

4211283−4/E 08/12

NOTES: A. All linear dimensions are in millimeters.
          B. This drawing is subject to change without notice.
          C. Publication IPC−7351 is recommended for alternate designs.
          D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
              contact their board assembly site for stencil design recommendations. Refer to IPC−7525 for other stencil recommendations.
          E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

NS (R-PDSO-G)**   PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN

DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES: A.   All linear dimensions are in millimeters.
         B.   This drawing is subject to change without notice.
         C.   Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DIM PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

B

14   8

C

1   7

0.065 (1,65)
0.045 (1,14)

0.005 (0,13) MIN

0.060 (1,52)
0.015 (0,38)

0.200 (5,08) MAX

Seating Plane

0.130 (3,30) MIN

A

0°−15°

0.026 (0,66)
0.014 (0,36)

0.100 (2,54)

0.014 (0,36)
0.008 (0,20)

4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).
         B. This drawing is subject to change without notice.
         C. This package is hermetically sealed with a ceramic lid using glass frit.
         D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
         E. Falls within MIL STD 1835 GDIP1−T14, GDIP1−T16, GDIP1−T18 and GDIP1−T20.

DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	——	——	——	——
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

B

14   8

1   7

0.065 (1,65)
0.045 (1,14)

0.005 (0,13) MIN

0.060 (1,52)
0.015 (0,38)

0.200 (5,08) MAX

Seating Plane

0.130 (3,30) MIN

0.026 (0,66)
0.014 (0,36)

0.100 (2,54)

A

0°-15°

0.014 (0,36)
0.008 (0,20)

4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).
         B. This drawing is subject to change without notice.
         C. This package is hermetically sealed with a ceramic lid using glass frit.
         D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
         E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE

PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD

A

16   9

0.260 (6,60)
0.240 (6,10)

1   8

0.070 (1,78)
0.045 (1,14) △D

0.045 (1,14)
0.030 (0,76) △D

0.020 (0,51) MIN

0.200 (5,08) MAX

Seating Plane

0.125 (3,18) MIN

0.100 (2,54)

0.021 (0,53)
0.015 (0,38)

⊕ 0.010 (0,25) Ⓜ

14/18 Pin Only
20 Pin vendor option △D

0.325 (8,26)
0.300 (7,62)

0.015 (0,38)

Gauge Plane

0.010 (0,25) NOM

0.430 (10,92) MAX

4040049/E   12/2002

NOTES: A.   All linear dimensions are in inches (millimeters).
B.   This drawing is subject to change without notice.
△C   Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
△D   The 20 pin end lead shoulder width is a vendor option, either half or full width.

TEXAS
INSTRUMENTS
www.ti.com

SOIC

10.63 / **9.97** TYP

A

PIN 1 ID
AREA

1

18X 1.27

20

13.0 / 12.6
NOTE 3

2X 11.43

10

11

7.6 / 7.4
NOTE 4

B

20X 0.51 / 0.31

⊕ 0.25Ⓜ C A B

C

SEATING PLANE

◯ 0.1 C

2.65 MAX

0.33 / 0.10 TYP

SEE DETAIL A

0.25
GAGE PLANE

0° - 8°

1.27 / 0.40

0.3 / 0.1

DETAIL A
TYPICAL

4220724/A   05/2016

NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

20X (2)

SYMM

1

20X (0.6)

18X (1.27)

20

SYMM

(R0.05)
TYP

10

11

(9.3)

LAND PATTERN EXAMPLE
SCALE:6X

SOLDER MASK
OPENING

METAL

METAL UNDER
SOLDER MASK

SOLDER MASK
OPENING

0.07 MAX
ALL AROUND

0.07 MIN
ALL AROUND

NON SOLDER MASK
DEFINED

SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4220724/A   05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

TEXAS
INSTRUMENTS
www.ti.com

20X (2)

1

20X (0.6)

18X (1.27)

SYMM

20

SYMM

11

10

(9.3)

SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A   05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate
   design recommendations.
9. Board assembly site may have different recommendations for stencil design.

IMPORTANT NOTICE

Texas Instruments Incorporated (TI) reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete.

TI's published terms of sale for semiconductor products (http://www.ti.com/sc/docs/stdterms.htm) apply to the sale of packaged integrated circuit products that TI has qualified and released to market. Additional terms may apply to the use or sale of other types of TI products and services.

Reproduction of significant portions of TI information in TI data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such reproduced documentation. Information of third parties may be subject to additional restrictions. Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyers and others who are developing systems that incorporate TI products (collectively, "Designers") understand and agree that Designers remain responsible for using their independent analysis, evaluation and judgment in designing their applications and that Designers have full and exclusive responsibility to assure the safety of Designers' applications and compliance of their applications (and of all TI products used in or for Designers' applications) with all applicable regulations, laws and other applicable requirements. Designer represents that, with respect to their applications, Designer has all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. Designer agrees that prior to using or distributing any applications that include TI products, Designer will thoroughly test such applications and the functionality of such TI products as used in such applications.

TI's provision of technical, application or other design advice, quality characterization, reliability data or other services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, "TI Resources") are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using TI Resources in any way, Designer (individually or, if Designer is acting on behalf of a company, Designer's company) agrees to use any particular TI Resource solely for this purpose and subject to the terms of this Notice.

TI's provision of TI Resources does not expand or otherwise alter TI's applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

Designer is authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED "AS IS" AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS. TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY DESIGNER AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

Unless TI has explicitly designated an individual product as meeting the requirements of a particular industry standard (e.g., ISO/TS 16949 and ISO 26262), TI is not responsible for any failure to meet such industry standard requirements.

Where TI specifically promotes products as facilitating functional safety or as compliant with industry functional safety standards, such products are intended to help enable customers to design and create their own applications that meet applicable functional safety standards and requirements. Using products in an application does not by itself establish any safety features in the application. Designers must ensure compliance with safety-related requirements and standards applicable to their applications. Designer may not use any TI products in life-critical medical equipment unless authorized officers of the parties have executed a special contract specifically governing such use. Life-critical medical equipment is medical equipment where failure of such equipment would cause serious bodily injury or death (e.g., life support, pacemakers, defibrillators, heart pumps, neurostimulators, and implantables). Such equipment includes, without limitation, all medical devices identified by the U.S. Food and Drug Administration as Class III devices and equivalent classifications outside the U.S.

TI may expressly designate certain products as completing a particular qualification (e.g., Q100, Military Grade, or Enhanced Product). Designers agree that it has the necessary expertise to select the product with the appropriate qualification designation for their applications and that proper product selection is at Designers' own risk. Designers are solely responsible for compliance with all legal and regulatory requirements in connection with such selection.

Designer will fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of Designer's non-compliance with the terms and provisions of this Notice.